

MESFET

(Metal Semiconductor Field Effect Transistor)

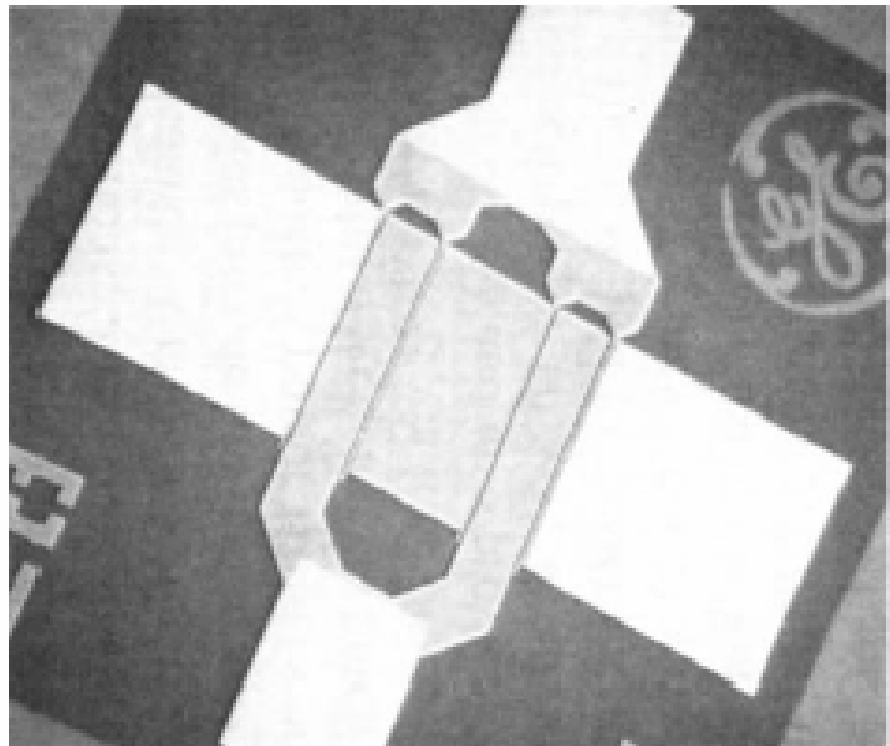
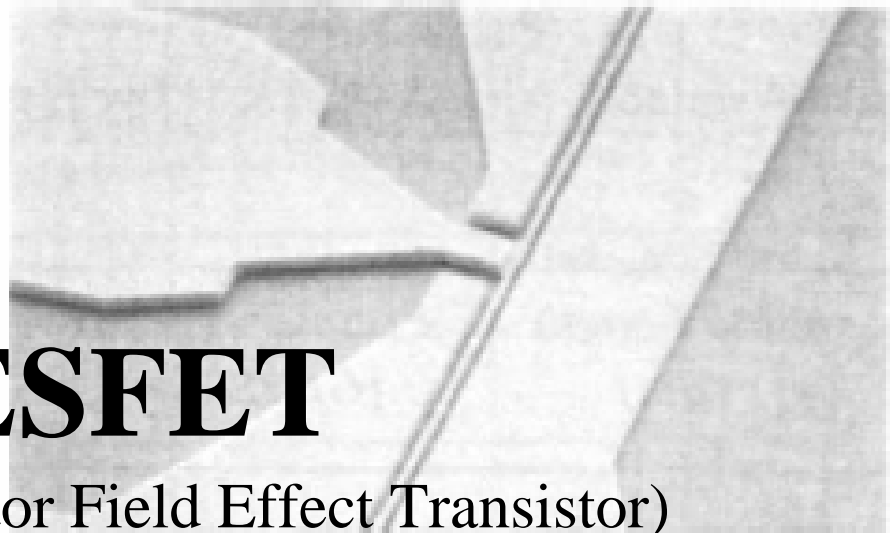
Stephen Nowell

gth253a

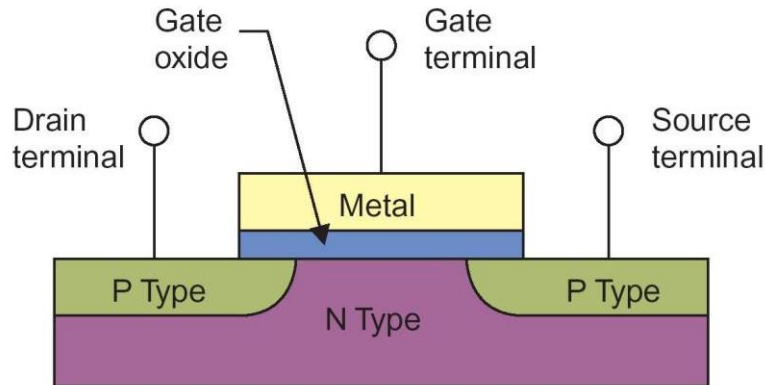
ECE 3080

Spring 2008

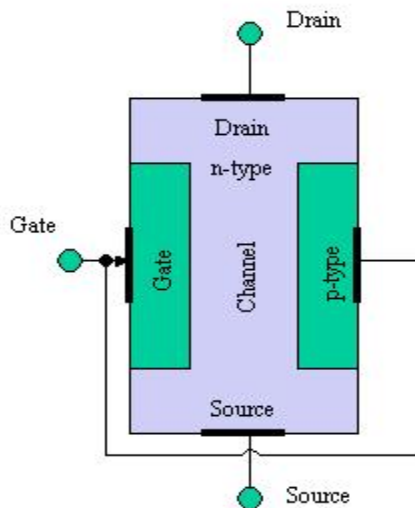
W.Alan Doolittle



Quick Comparison to Other FETS

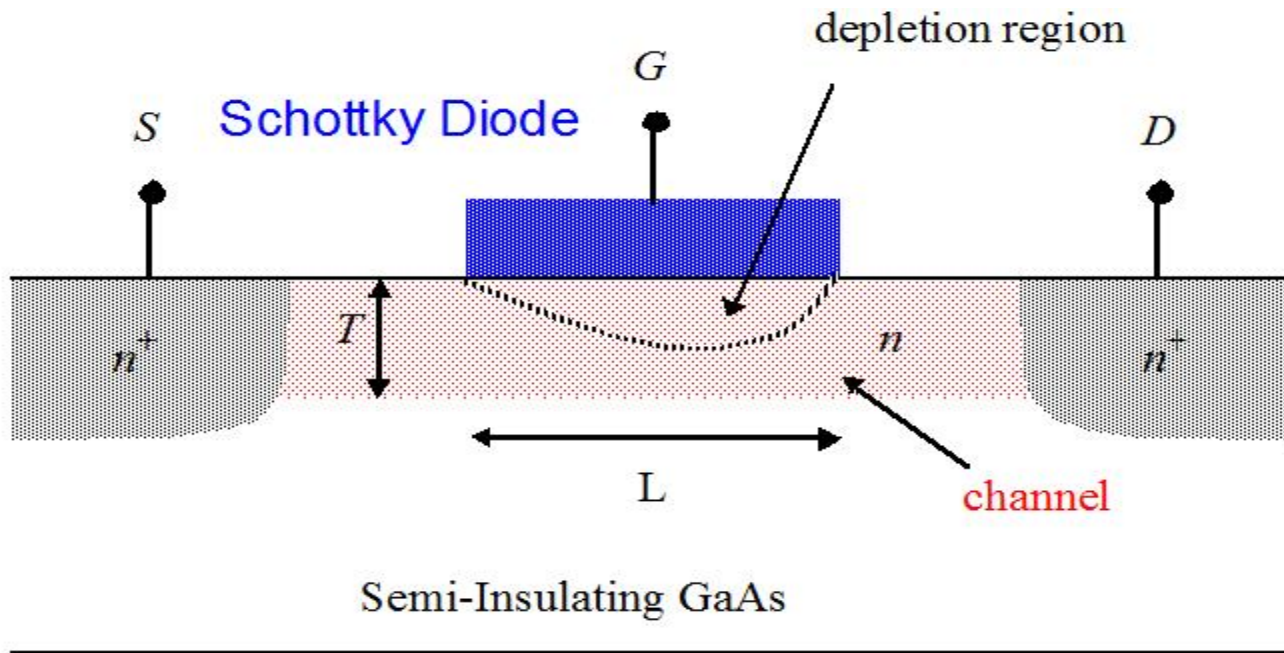


- MOSFETs form a channel with inversion and have an oxide gate.



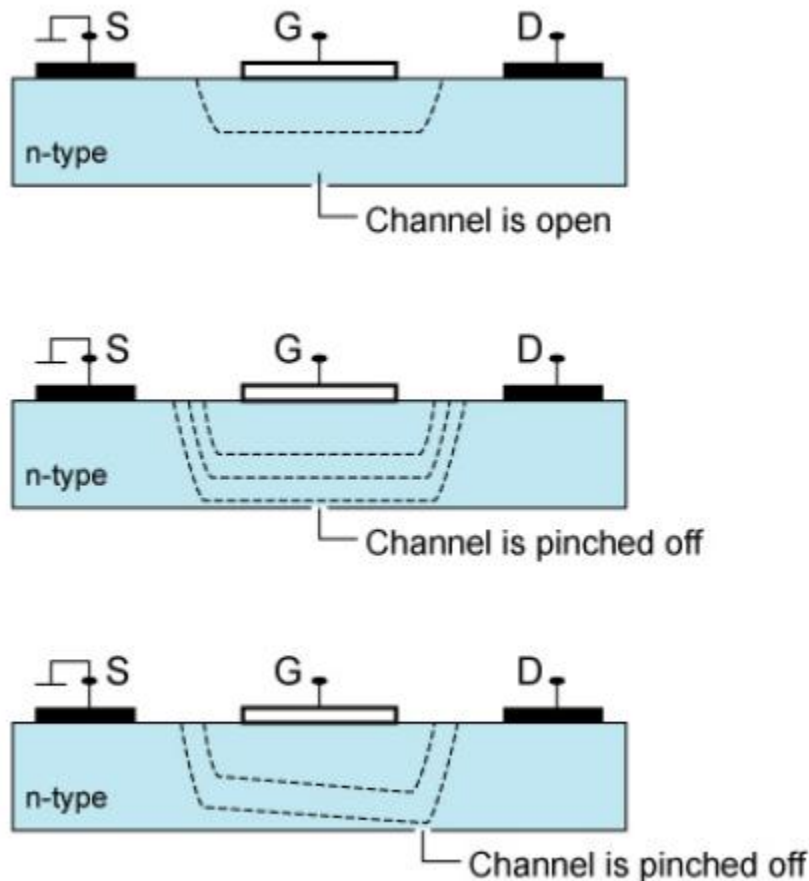
- JFETs deplete the channel to cut off current flow.

The MESFET



- MESFETs (MEtal Semiconductor Field Effect Transistor) have a metal gate, not oxide, and work similar to JFETs by pinching off the conducting channel.

Bias on the MESFET

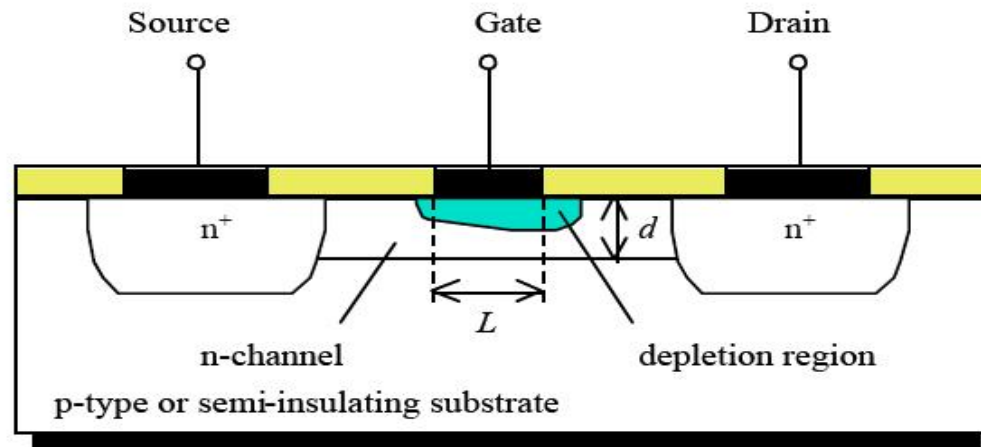


- With no voltage's applied electrons are not inhibited or motivated to flow.

- No voltage across source and drain, but reverse bias on the gate. With enough reverse bias channel is pinched and no electrons can flow.

- Voltage across the drain and source create a current and cause the depletion region to pinch off sooner on the drain side.

Calculations



$$V_T = \phi_i - V_P$$

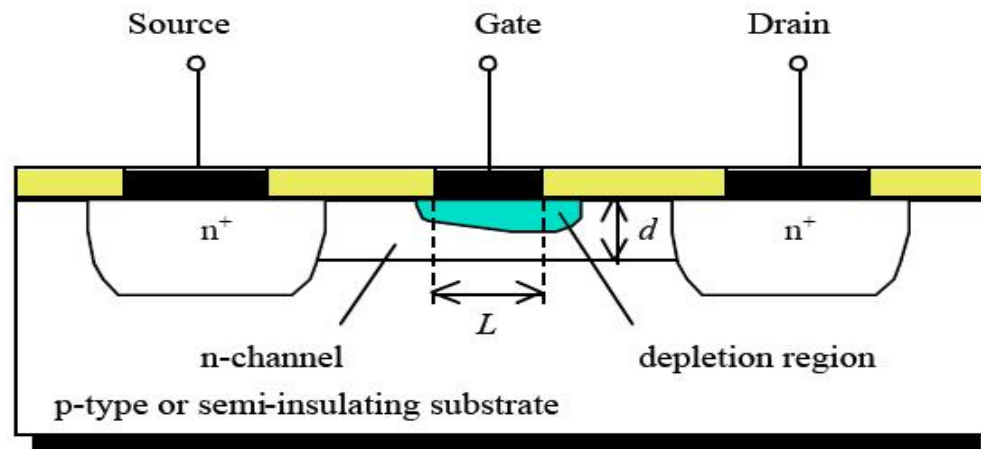
- V_T is the threshold voltage required to fully deplete the doped channel layer.

$$V_P = \frac{qN_d d^2}{2\epsilon_s}$$

- V_P is the pinch-off voltage.

- ϕ_i is the built in potential.

Calculations cont.



$$J = qnv = qN_d\mu_n E$$

- Current density in the doped layer

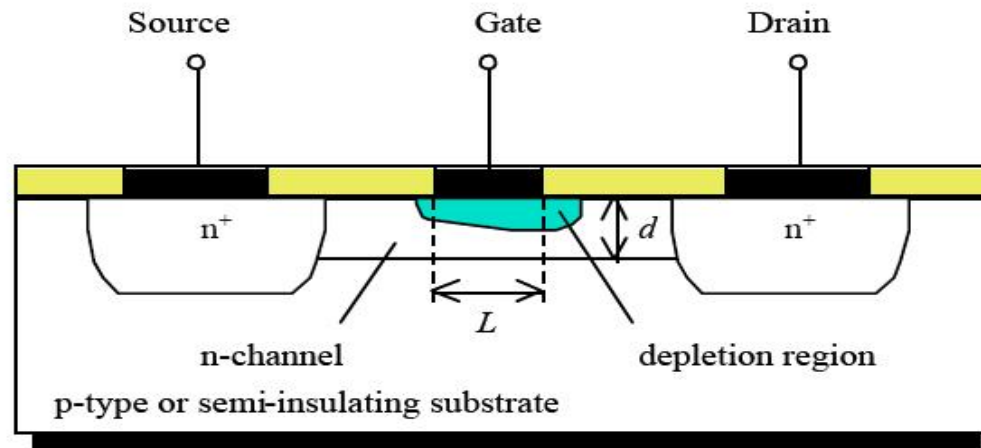
$$I_D = -JW(d - x_n(y))$$

- Current in the doped layer

$$x_n(y) = \sqrt{\frac{2\epsilon_s(\phi_i - V_G + V_C(y))}{qN_d}}$$

- Depletion layer width of the depletion region.

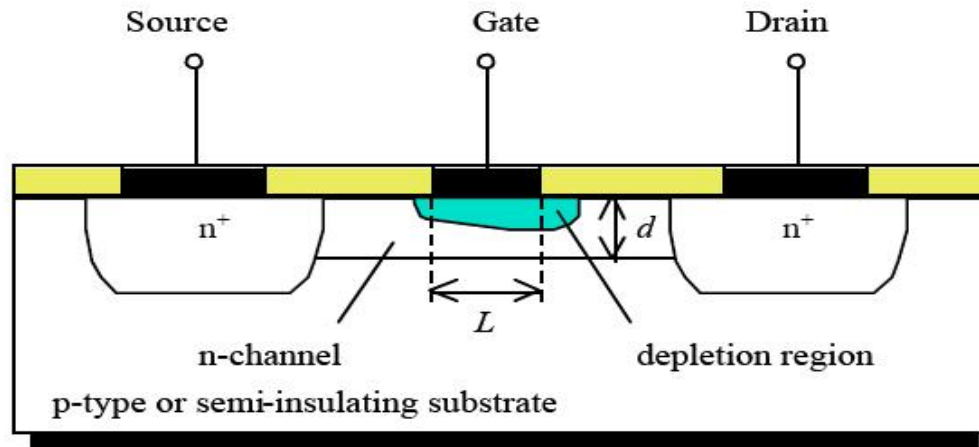
Calculations cont.



$$\int_0^L I_D dy = qN_d\mu_n dW \int_0^{V_D} \left(1 - \sqrt{\frac{\phi_i - V_G + V_C}{V_P}}\right) dV_C$$

- Integrating from the source to the drain we can calculate the current of the MESFET

Calculations cont.

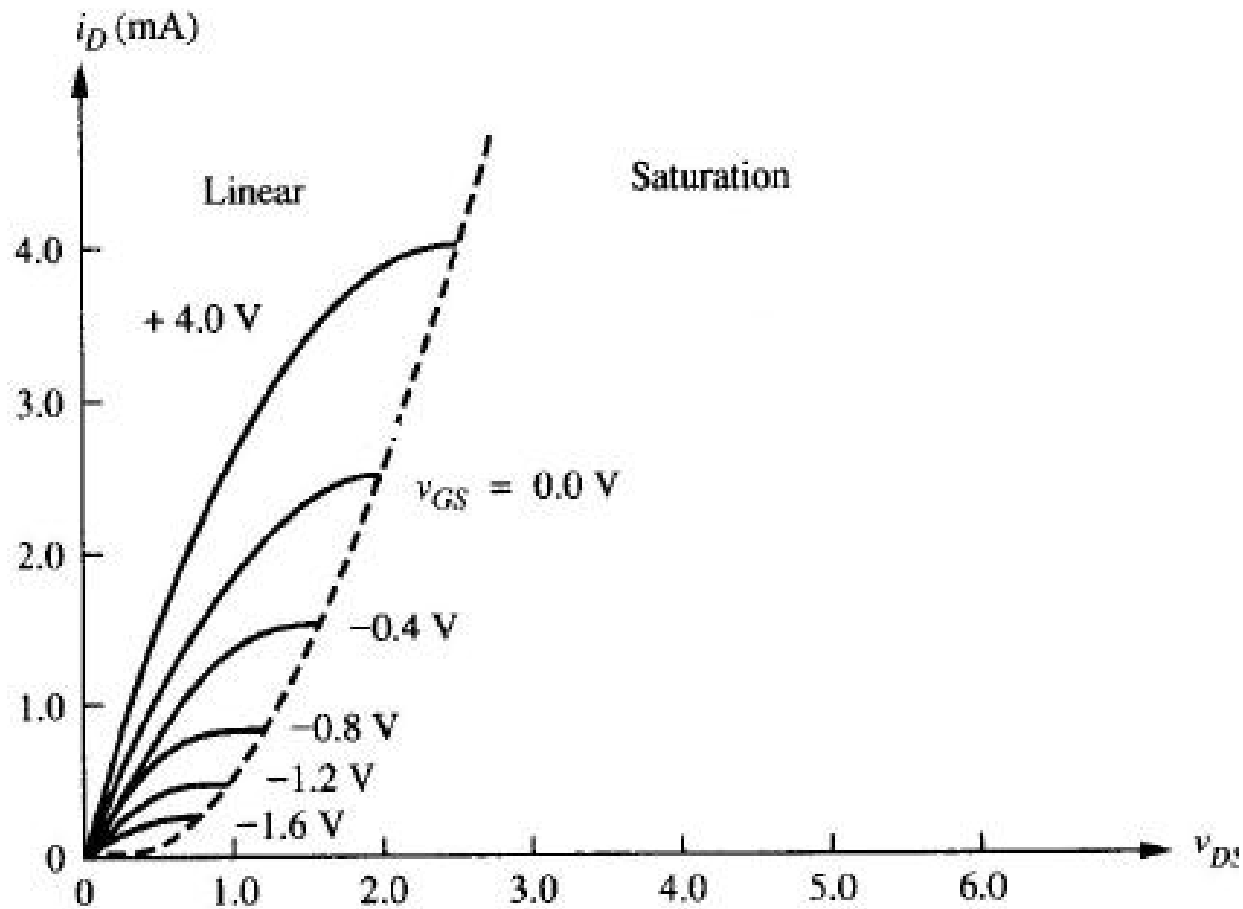


$$I_D = qN_d\mu_n d \frac{W}{L} \left(V_C \Big|_0^{V_D} - \frac{(\phi_i - V_G + V_C)^{3/2}}{\sqrt{V_P}} \Big|_0^{V_D} \right)$$

$$I_D = q\mu_n N_d d \frac{W}{L} \left[V_D - \frac{2}{3} \left(\frac{(\phi_i - V_G + V_D)^{3/2}}{\sqrt{V_P}} - \frac{(\phi_i - V_G)^{3/2}}{\sqrt{V_P}} \right) \right]$$

- Equations are valid for $V_D \leq V_G - V_T$

Linear Region of the MESFET

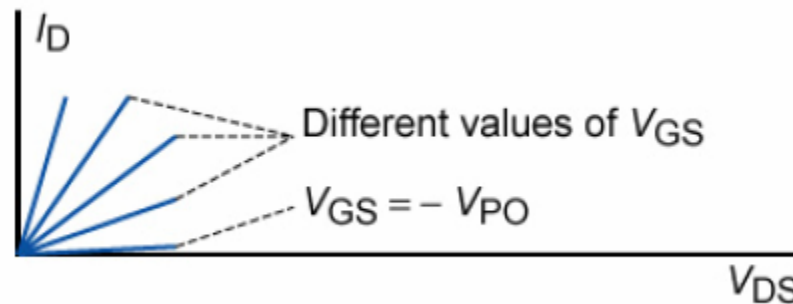


Resistance in the Channel

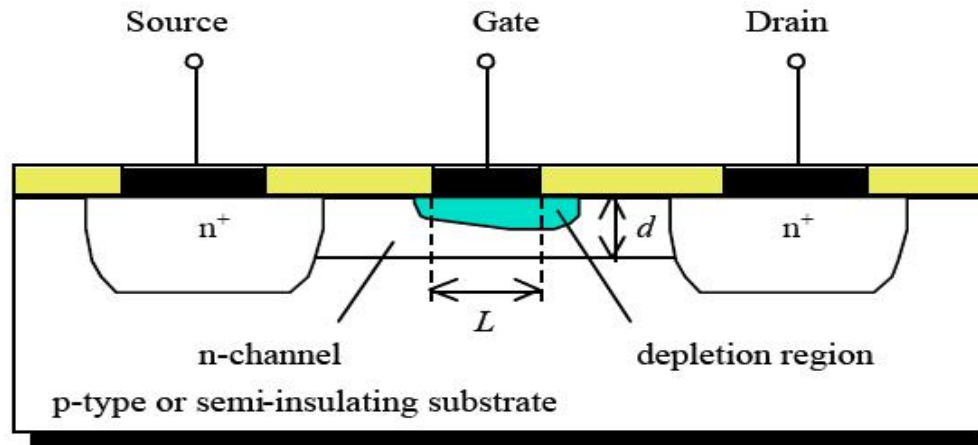
$$R = \rho \frac{L_G}{A} = \rho \frac{L_G}{Z h(x)} = \frac{1}{en\mu} \frac{L_G}{Z (W_{ch} - W_D)}$$

$$R = \frac{1}{en\mu} \frac{L_G}{Z \left(W_{ch} - \sqrt{\frac{2\epsilon}{eN_D} (-V_{GS})} \right)}$$

- Resistance can be controlled by the gate voltage in the triode region. At $V_{GS} = -V_{PO}$ the resistance of the channel is infinite.



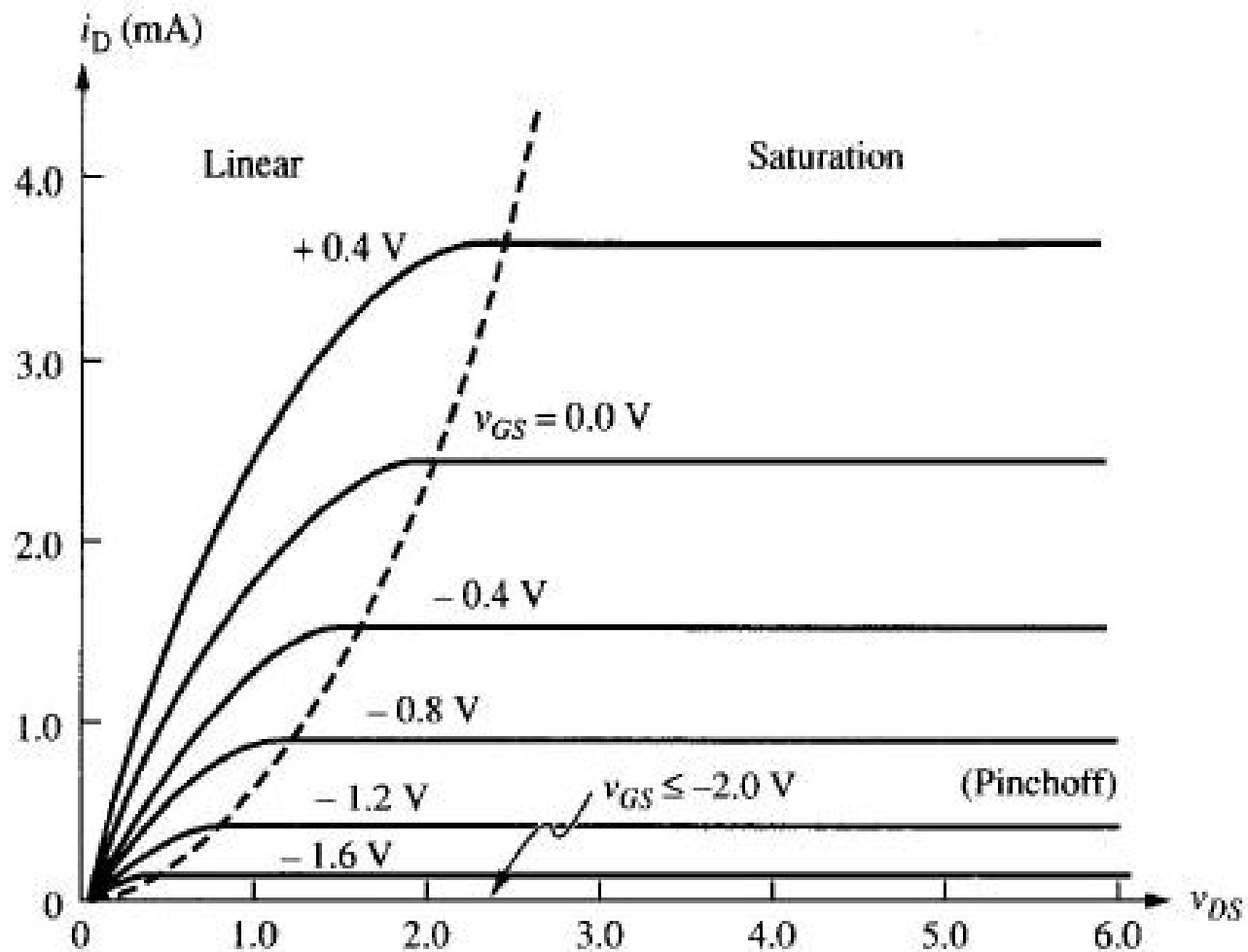
More calculations



- For the condition when: $V_D = V_G - V_T = V_{D,sat}$
- The current saturates described by the following current equation for saturation current

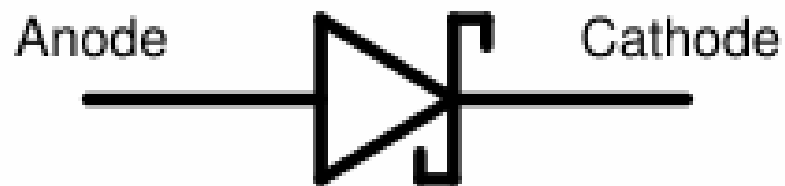
$$I_{D,sat} = q\mu_n N_d d \frac{W}{L} \left[V_G - V_T - \frac{2}{3} \left(V_P - \frac{(\phi_i - V_G)^{3/2}}{\sqrt{V_P}} \right) \right]$$

Saturation Region

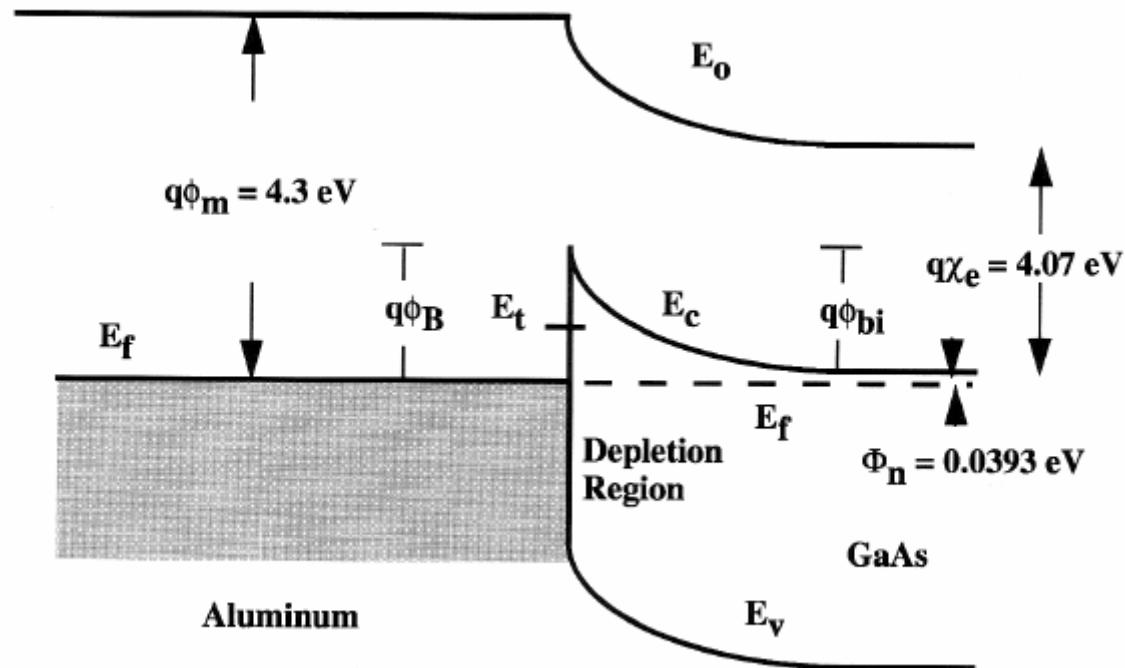


Schottky Diode

- The metal contact of the gate creates a schottky diode.
- The presence of the diode limits the forward bias voltage of the gate to that of the diode turn on voltage.

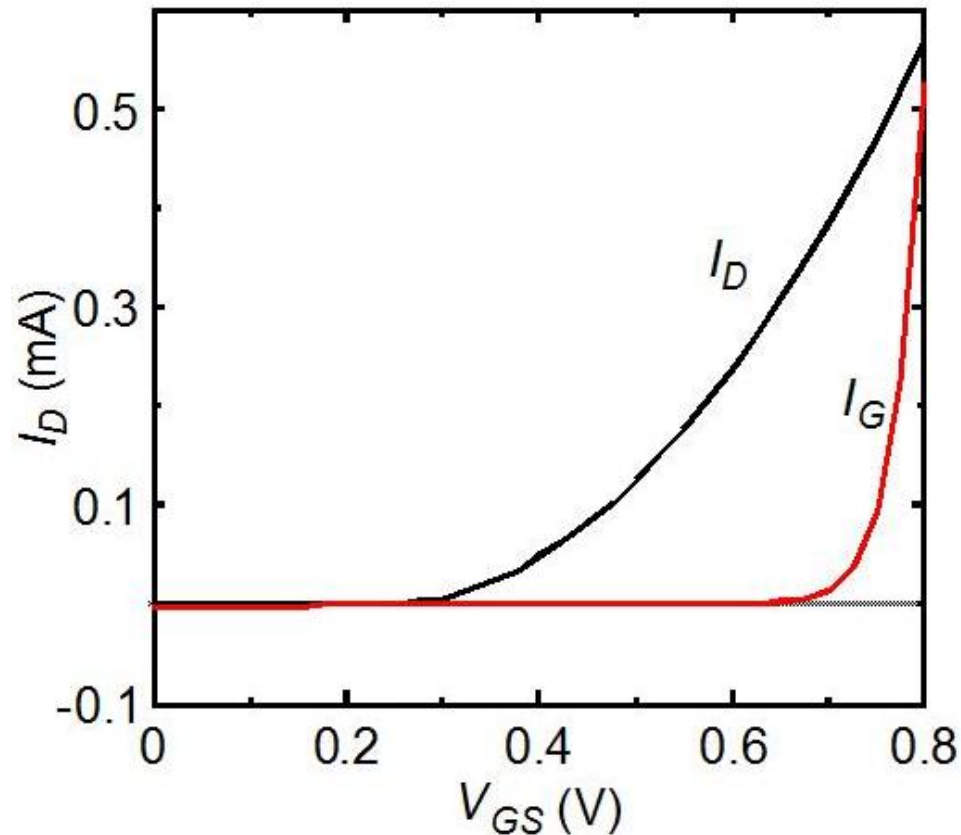


Schottky Barrier



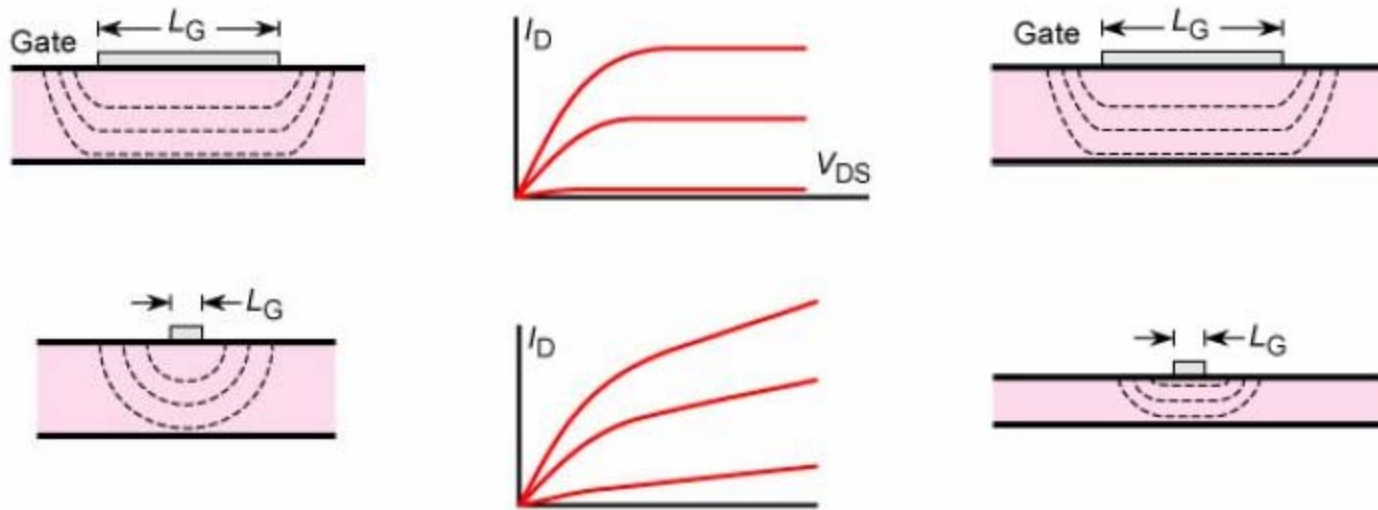
- The gate behaves the same as a schottky diode with the schottky barrier.

Diode Turned On



- When forward bias the diode turns on causing current to flow through the gate.

Other Considerations

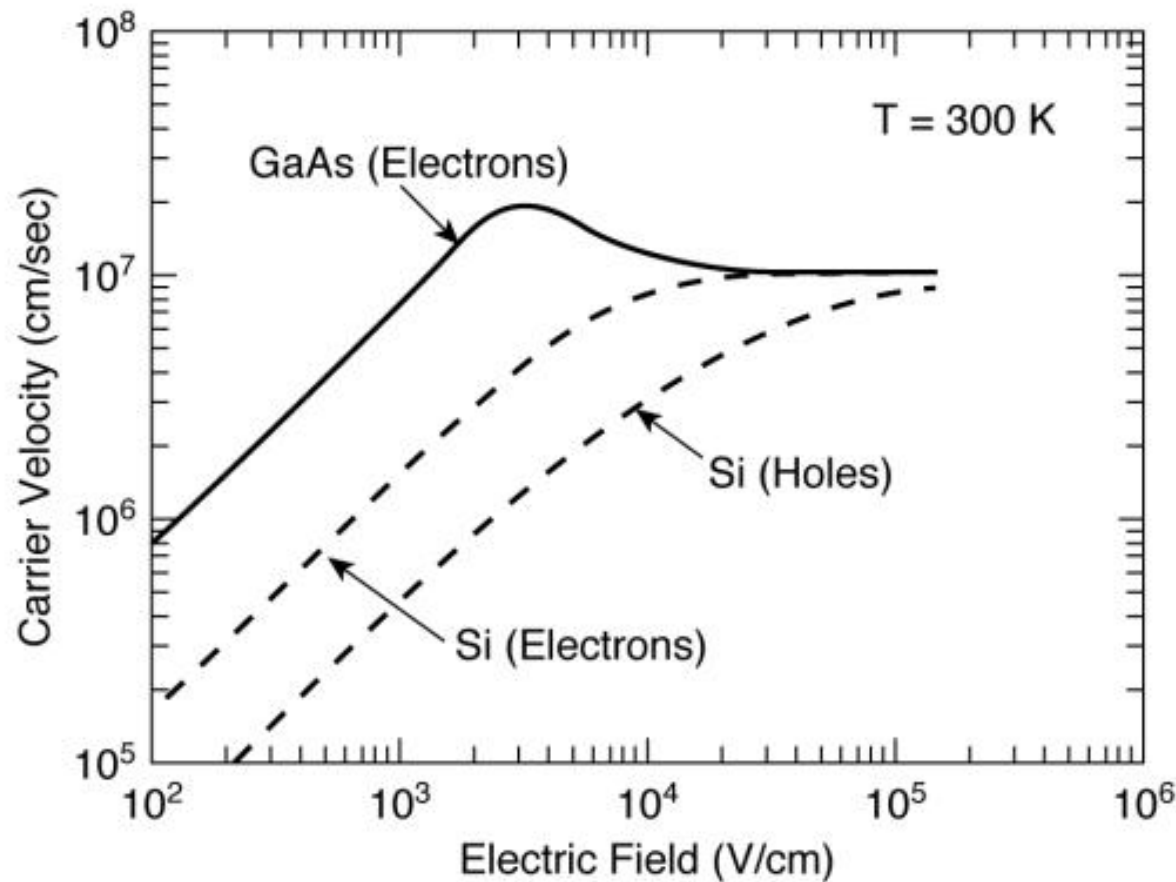


- Short-channel effect on depletion region. Selecting a gate that's too small will not pinch off properly but this can be corrected by adjusting the depth of the channel, doping, or fields strength.

Advantages

- Higher surface mobility of the carriers in the channel vs. MOSFET because carriers don't go into the oxide.
- The depletion region separates the carriers from the surface.
- Can increase mobility by using GaAs over silicon MESFETs.
- Ease of fabrication compared to other FETs.

Mobility of GaAs



- Mobility of electrons GaAs (4000 – 9000) vs. Si (500 – 1200)
- Maximum electron velocity of GaAs is 2x silicon electrons.
- Schottky barrier height GaAs 0.6V-0.8V vs. Si 0.4V- 0.6V.

GaAs vs. Silicon cont.

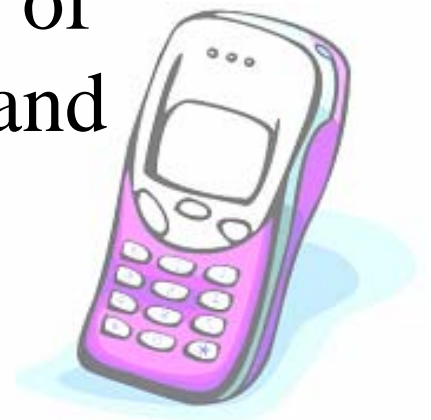
- Very low hole mobility GaAs $400 \text{ cm}^2/\text{V}\cdot\text{sec}$ vs. silicon $489 \text{ cm}^2/\text{V}\cdot\text{sec}$ meaning no complementary gates.
- Possible to fabricate semi-insulating GaAs substrates that eliminate the problem of absorbing microwave power in the substrate.
- Generally, if frequency $> 2\text{GHz}$ GaAs
if frequency $< 2\text{GHz}$ Si

Disadvantages

- Schottky Diode limits forward active to turn on of diode.
- Tend to have high leakage currents.
- P-type have low mobility (mostly n-type).
- For enhancement mode MESFETs the threshold voltage must be lower than turn-on of schottky diode turn on making it difficult to fabricate circuits containing large number of them (depletion mode is more commonly used).

High Frequency Devices

- Cell phones, satellite receivers, radar, microwave devices.
- Typically depletion-mode devices are used because they provide larger currents and larger transconductance.
- Buried channel yields a better noise performance vs. trapping and release of carriers into and from surface states and defects are eliminated.





Questions?

References and Additional Info

In addition to images, information was used from the following sources:

-http://ece-www.colorado.edu/~bart/book/book/chapter3/pdf/ch3_6.pdf

-<http://ece-www.colorado.edu/~bart/book/mesfet.htm> (Bart J. Van Zeghbroeck, 1998)

-<http://www.iue.tuwien.ac.at/phd/ayalew/node101.html> (*T. Ayalew: SiC Semiconductor Devices Technology, Modeling, and Simulation*)

-<http://books.google.com/books> (GaAs High-speed Devices: Physics, Technology, and Circuit Applications By C. Y. Chang, Francis Kai)

-<http://www.britannica.com/ebc/art-70994/MESFET-transistor-In-a-metal-semiconductor-field-effect-transistor-current>

-<http://ocw.mit.edu/NR/rdonlyres/Electrical-Engineering-and-Computer-Science/6-772Spring2003/6624143B-7CFF-4104-A127-43E3E3A4D0FC/0/Lecture9v2.pdf>
(C.G. Fonstad, 3/03)

-<http://www.ecse.rpi.edu/~schubert/Course-ECSE-6290%20SDM-2/1%20JFETs%20and%20MESFETs.pdf> (E.F.Schubert, Rensselaer Polytechnic Institute)

References Cont.

-http://www.eas.asu.edu/~vasilesk/EEE532/mesfet_1.pdf

-http://www.roke.co.uk/download/papers/SiC_MESFETs_for_Phased_Array_Radar_Applications.pdf (Evaluation of Commercially Available SiC Mesfets for Phased Array Radar Applications Mark G. Walden and Mathew Knight)

-Slide show “Very High Performance Logic” (Digital Integrated Circuits, High Speed, Prentice Hall 1995)

These URL's were taken and accurate on April 7th, 2008

All images are referenced on the bottom slide they were used.